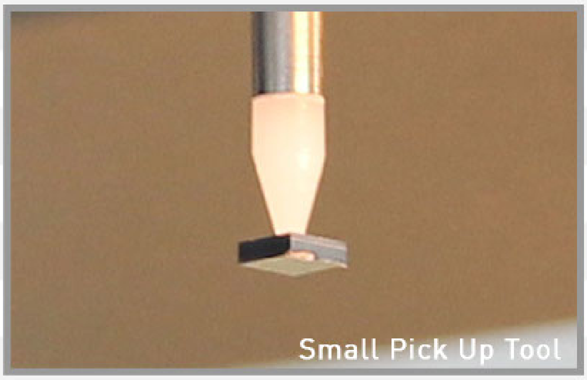
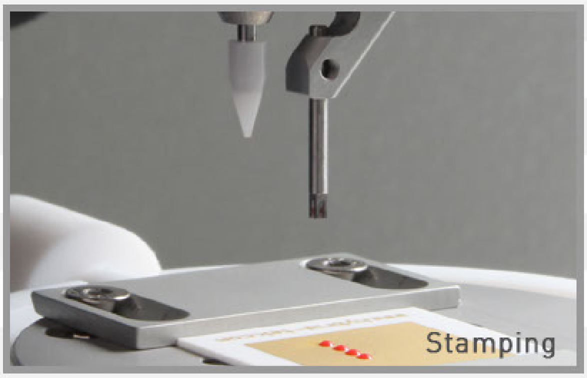
HB70 Manual Die Bonder

Motorized Z- Axis


Small Pick Up Tool


Stamping

- + Compact and easy to use
- + Motorized and programmable Z-Axis
- + True vertical movement
- + HDMI camera with optical zoom
- + Adjustable viewing angle
- + Rotatable table
- + Fine adjustment screws for x-axis and y-axis
- + Epoxy dispensing or Epoxy stamping
- + Integrated vacuum pump
- + Force range: 1 - 100cN
- + Camera LEDs included

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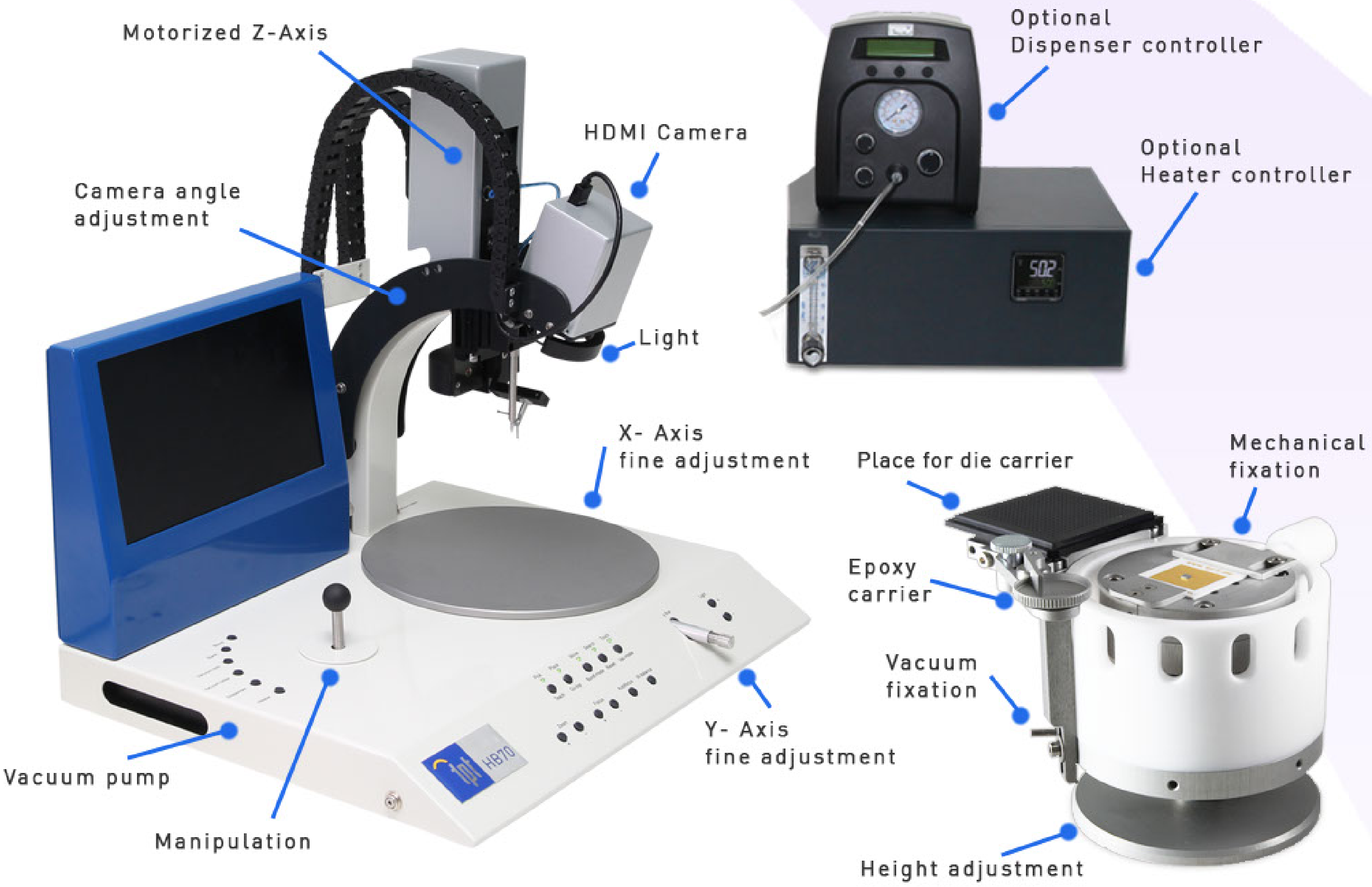
The HB70 is a **Bench Top Size Die Bonder**, ideal for laboratories, pilot and small scale production lines.
It is equipped with a double head for die-placement and for epoxy.
The epoxy can be pasted through epoxy stamping or epoxy dispensing.
The work holder fixates the substrate with vacuum power, has two die carrier holders
and an integrated spot heater. The heating curve can be programmed on a special controller.
Different pick-up holders allow the usage of all kinds of tool diameters.
The machine can be easily tailored towards your die-bonding needs.

Applications

+ Die bonding
+ MEMS / MOEMS assembly
+ Sensor assembly
+ Optical components assembly
+ Assembly and handling of mechanical components
+ Applications in the field of medical technology

Technical Specification

+ Electrical Requirements 100-240 Volt
+ Dimensions: 470mm x 380mm x 430mm
+ Weight: 22kg




Dispenser


Stamping tool


Pick up tool holder


Inert gas welding chamber

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